

50 ohm balun transformer for 2G45 ISM matched Nordic Semiconductor chips with ultralow power transceivers

Datasheet – production data

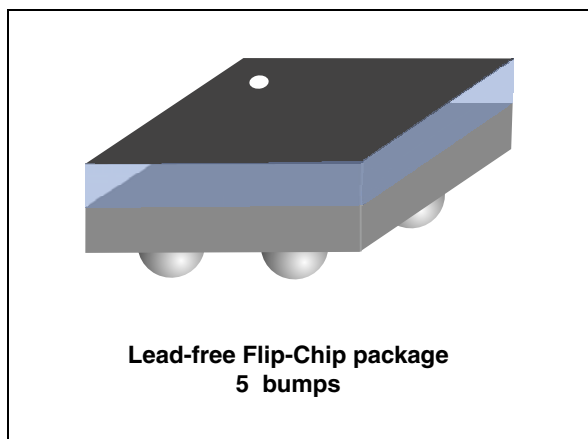
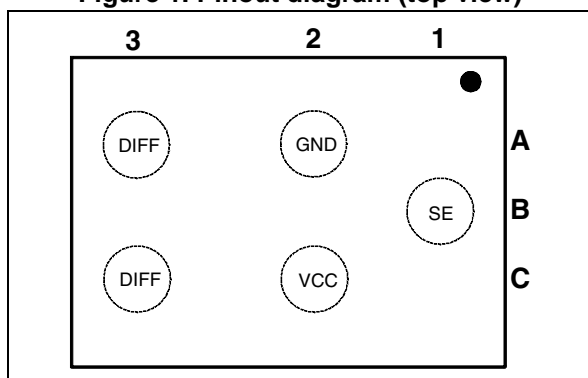


Figure 1. Pinout diagram (top view)



Features

- 50 Ω nominal input / conjugate match to Nordic Semiconductor chips nRF24LE1 QFN32, nRF24AP2-1CH, nRF24AP2-8CH, nRF51422 and nRF51822
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint: < 1.5 mm²

Benefits

- Very low profile: < 595 μ m after reflow
- High RF performance
- RF BOM and area reduction

Applications

- 2.45 GHz impedance matched balun filter
- Optimized for Nordic's chip set nRF24LE1/AP2 and nRF51 series

Description

STMicroelectronics BAL-NRF01D3 is an ultraminiature balun. The BAL-NRF01D3 integrates matching network and harmonics filter. Matching impedance has been customized for the following Nordic Semiconductor circuits: nRF24LE1 QFN-32 pins, nRF24AP2-1CH, nRF24AP2-8CH, nRF51422 and nRF51822.

The BAL-NRF01D3 uses STMicroelectronics IPD technology on non-conductive glass substrate which optimize RF performances.

The BAL-NRF01D3 has been tested and approved by Nordic Semiconductor in their nRF2723 and nRF2752 nRFgo modules.

1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
P _{IN}	Input Power RFIN			20	dBm
V _{ESD}	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 kΩ, air discharge)	2000			V
	ESD ratings charge device model (JESD22-C101-C)	500			
	ESD ratings machine model (MM: C = 200 pF, R = 25 Ω, L = 500 nH)	200			
T _{OP}	Operating temperature	-40		+85	°C

Table 2. Impedances (T_{amb} = 25 °C)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
Z _{OUT}	Nominal differential output impedance		conjugate match to nRF24LE1/AP2, nRF51422, nRF51822		Ω
Z _{IN}	Nominal input impedance		50		Ω

Table 3. RF performance (T_{amb} = 25 °C)

Symbol	Parameter	Test condition	Value			Unit
			Min.	Typ.	Max.	
F	Frequency range (bandwidth)		2400		2540	MHz
I _L	Insertion loss in bandwidth			2.25		dB
R _L	Return loss in bandwidth			10		dB
φ _{imb}	Phase imbalance			3		°
A _{imb}	Amplitude imbalance			0.1		dB
2f ₀	2nd harmonic filtering	4880 MHz		10		dB
3f ₀	3rd harmonic filtering	7320 MHz		20		dB

1.1 On-board simulations

Figure 2. Transmission ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

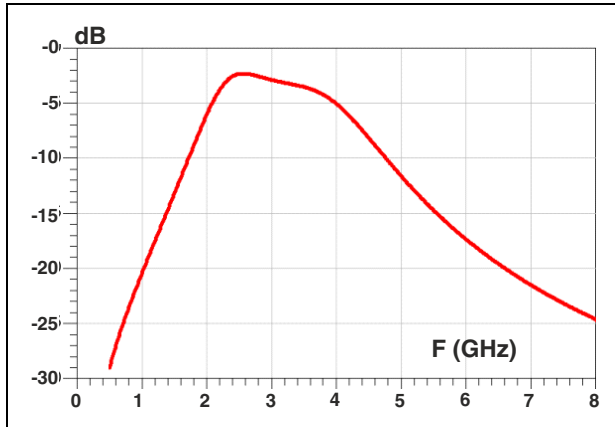


Figure 3. Return loss on SE port ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

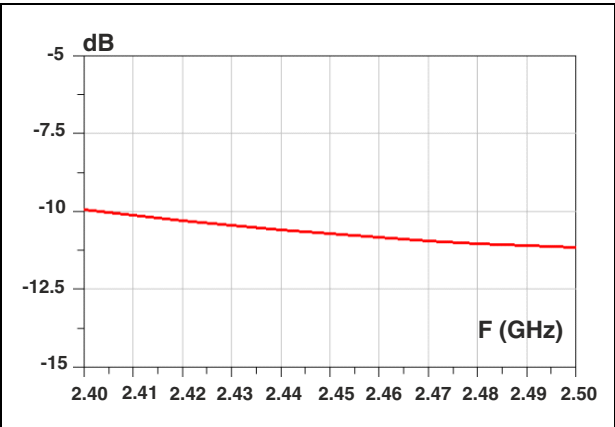


Figure 4. Return loss on DIFF port ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

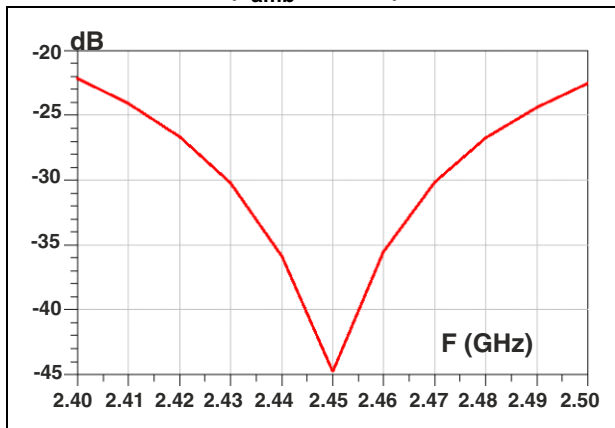


Figure 5. Amplitude imbalance ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

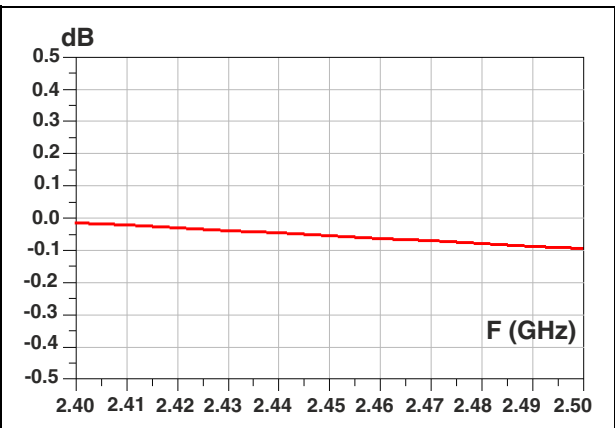
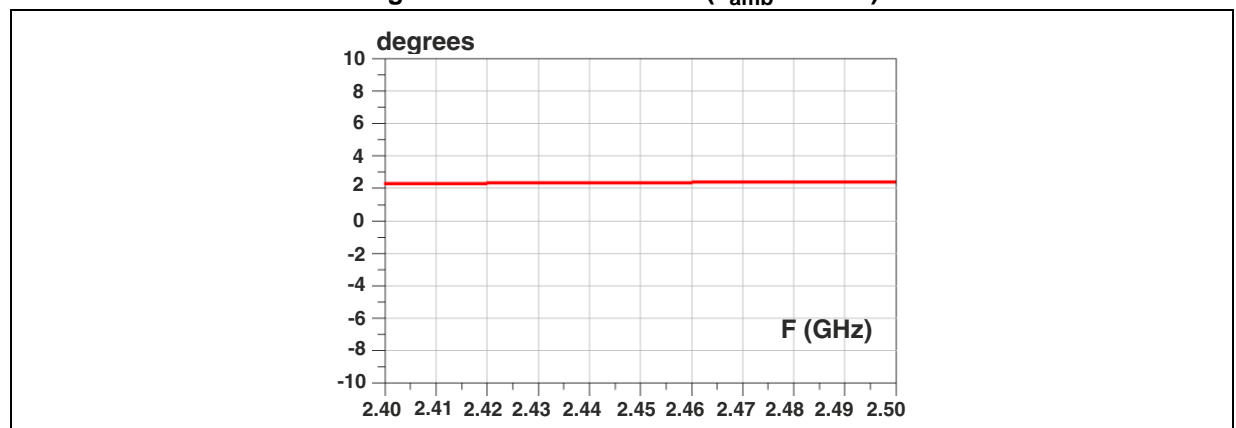


Figure 6. Phase imbalance ($T_{amb} = 25\text{ }^{\circ}\text{C}$)



2 Application information

Figure 7. Application schematic (courtesy of Nordic Semiconductor)

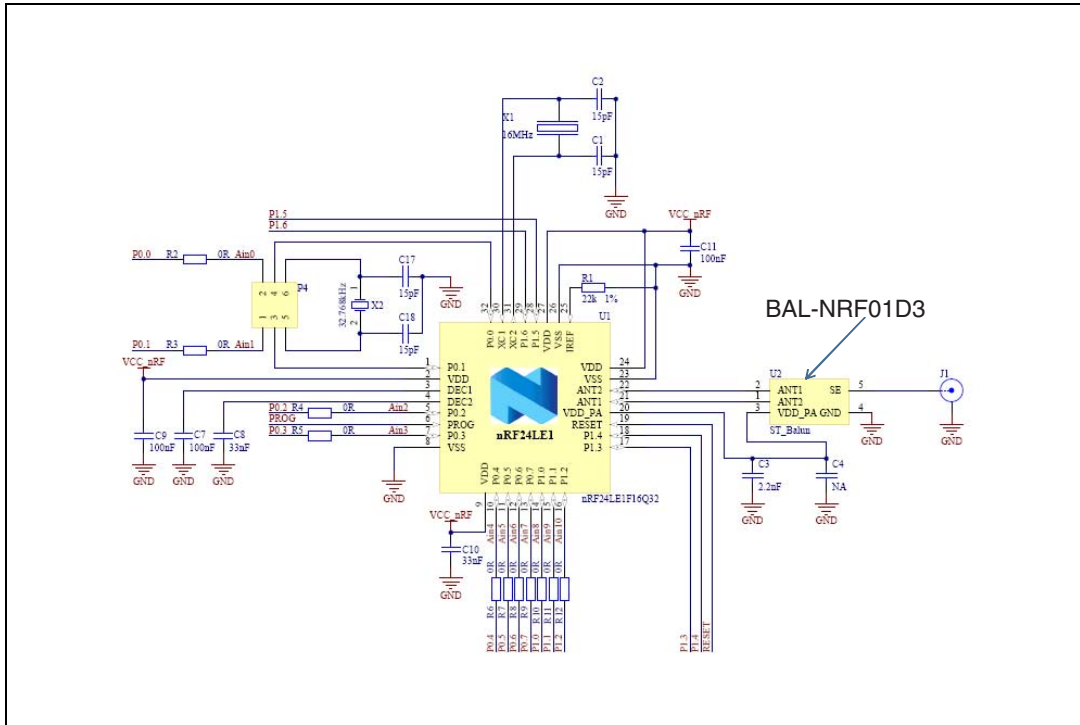


Figure 8. nRF2723 application board (courtesy of Nordic Semiconductor)

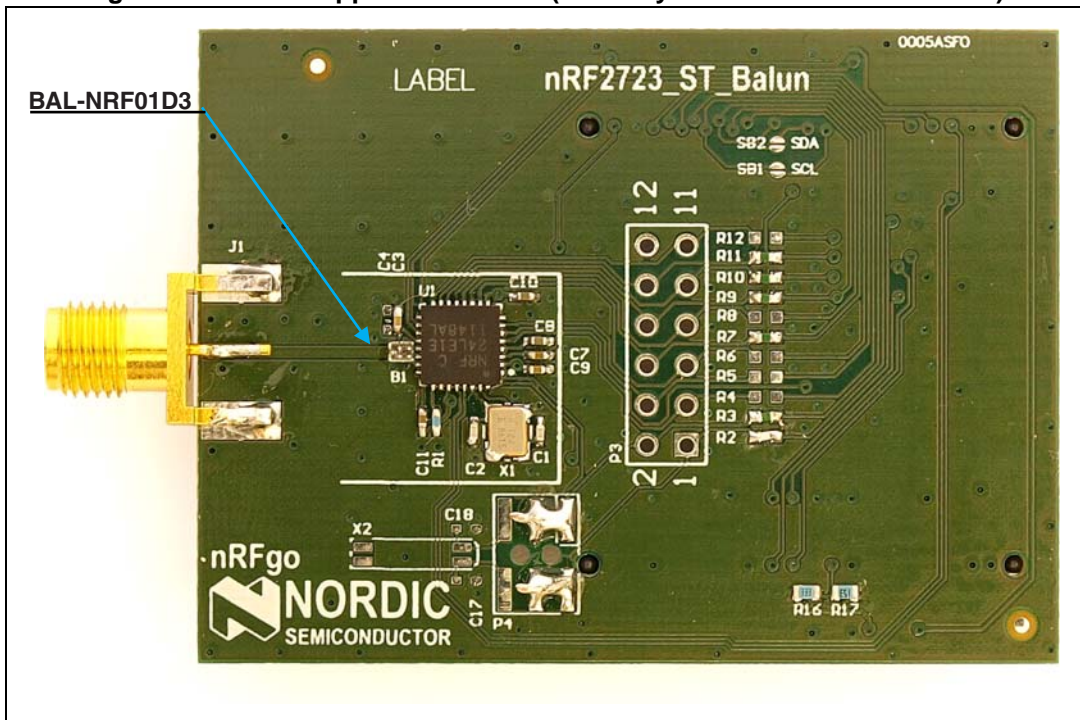


Figure 9. nRF2752 application board (courtesy of Nordic Semiconductor)



3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 10. Package dimensions (top and side view)

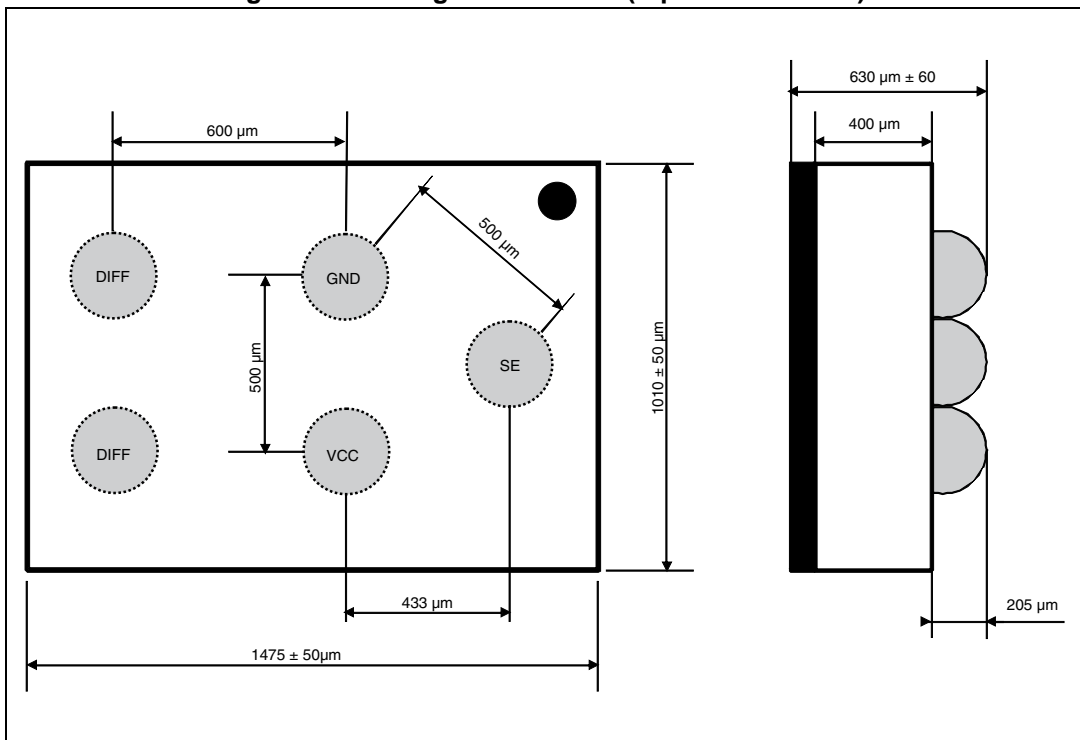


Figure 11. Footprint - non solder mask defined

Figure 12. Footprint - solder mask defined

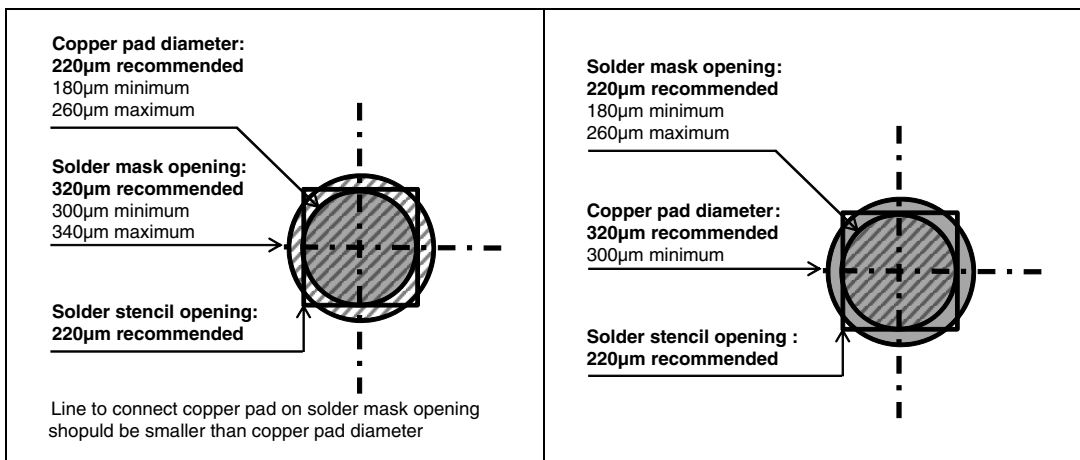


Figure 13. Marking

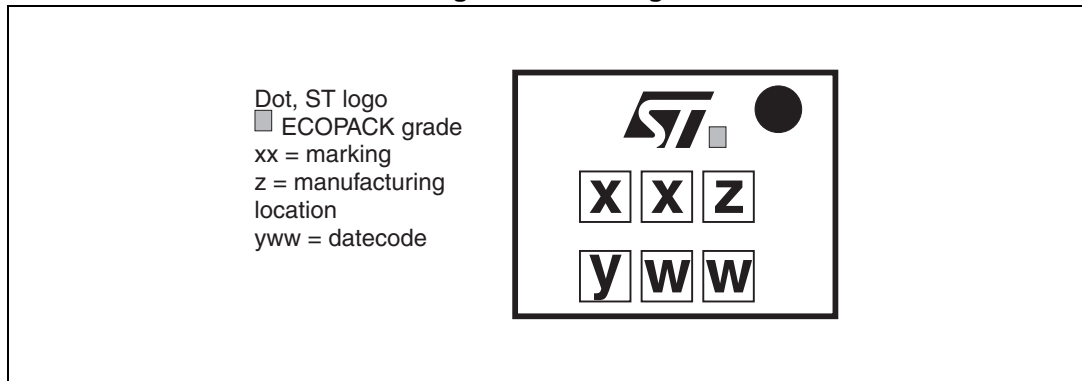
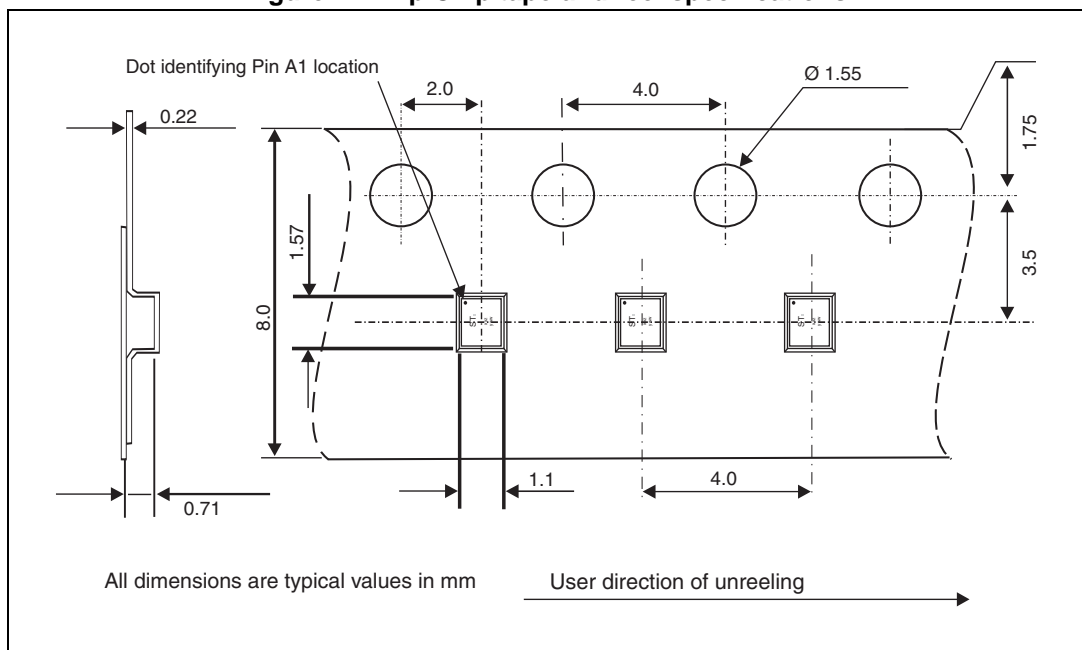


Figure 14. Flip Chip tape and reel specifications



Note: More information is available in the STMicroelectronics Application notes:
AN2348 Flip-Chip: "Package description and recommendations for use"
AN4111: "BAL-NRF01D3 matched balun with integrated harmonics filter for Nordic Semiconductor chips with ultralow power transceivers"

4 Ordering information

Table 4. Ordering information

Order code	Marking	Weight	Base Qty	Delivery mode
BAL-NRF01D3	SC	1.82 mg	5000	Tape and Reel

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
15-Oct-2012	1	Initial release
13-Nov-2012	2	Added references to nRF51 series. Added Figure 9 . Updated y-axis labels in Figure 2 .
04-Mar-2013	3	Updated footprint illustrations in Figure 11 , and Figure 12 .

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